

(1.27 mm) .050"

SEAFP-50-01-L-10-RA-WT-GP

SEAFP-RA SERIES

HIGH-DENSITY PRESS-FIT OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAFP-RA

Insulator Material:

Natural LCP

Contact Material:

Copper Alloy

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

1.3 A per pin
(10 adjacent pins powered)

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Working Voltage:

195 VAC/ 275 VDC

Mates with:

SEAM, SEAM-RA, SEAMP

Edge Rate®
contact

8 or 10 rows

Press-fit
tails

Optional
guide post holes

SEAFP	NO. OF POSITIONS	01	PLATING OPTION	NO. OF ROWS	RA	WT	OPTION
	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08 = Eight Rows -10 = Ten Rows		-WT =Weld Tab	-GP =Guide Post Hole

TOOLING

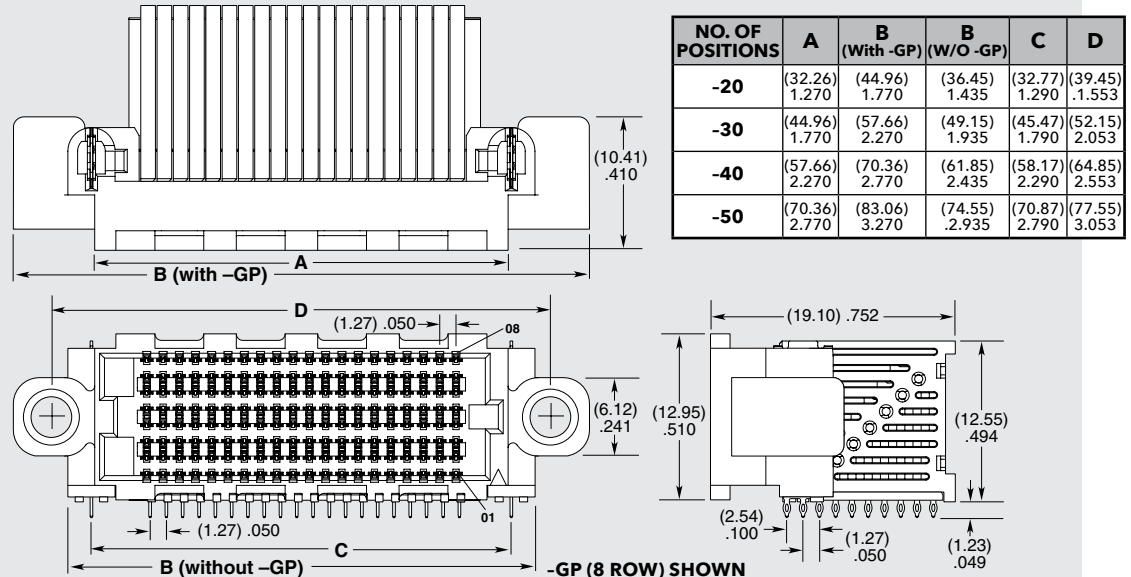
- Compliant pin fixture
CAT-SEAFP-XX-XX-RA

For more information,
visit www.samtec.com/tooling

Notes:

Applications with
varying board thickness
refer to Samtec compliant
pin termination specifications.

Some sizes, styles and
options are non-standard,
non-returnable.



WWW.SAMTEC.COM

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Samtec:](#)

[SEAFP-50-01-S-08-RA-WT](#) [SEAFP-20-01-L-08-RA-WT-GP](#) [SEAFP-40-01-S-10-RA-WT](#) [SEAFP-40-01-S-10-RA-WT-GP](#) [SEAFP-50-01-S-10-RA-WT-GP](#) [SEAFP-30-01-S-10-RA-WT-GP](#) [SEAFP-20-01-S-08-RA-WT-GP](#)